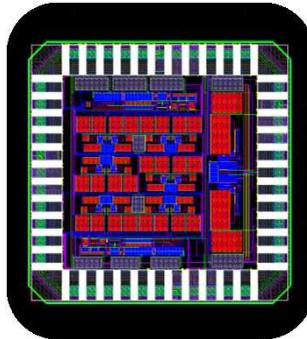
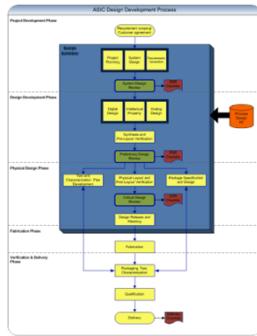


Exceptional service in the national interest



An overview of the Ultra-Fast X-ray Imager (UXI) program at Sandia Labs

L. Claus, L. Fang, R. Kay, M. Kimmel, J. Long,
G. Robertson, M. Sanchez, J. Stahoviak, D.
Trotter, J.L. Porter

8/13/2015



Sandia National Laboratories is a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000. SAND No. ####-####

Hybrid CMOS Camera System Motivation

Currently On NIF, Z, OMEGA → Image Plate & Film

Image Plate Disadvantages

- MCP front end required to time gate
- Multiple shots required to perform a time scan
- Measurement at a single point in time
- Expensive to process
- Issue with experimental reproducibility

Image Plate Replacement

Potential Future For All Facilities → Hybrid CMOS (hCMOS) Imager

Potential Hybrid CMOS Capabilities

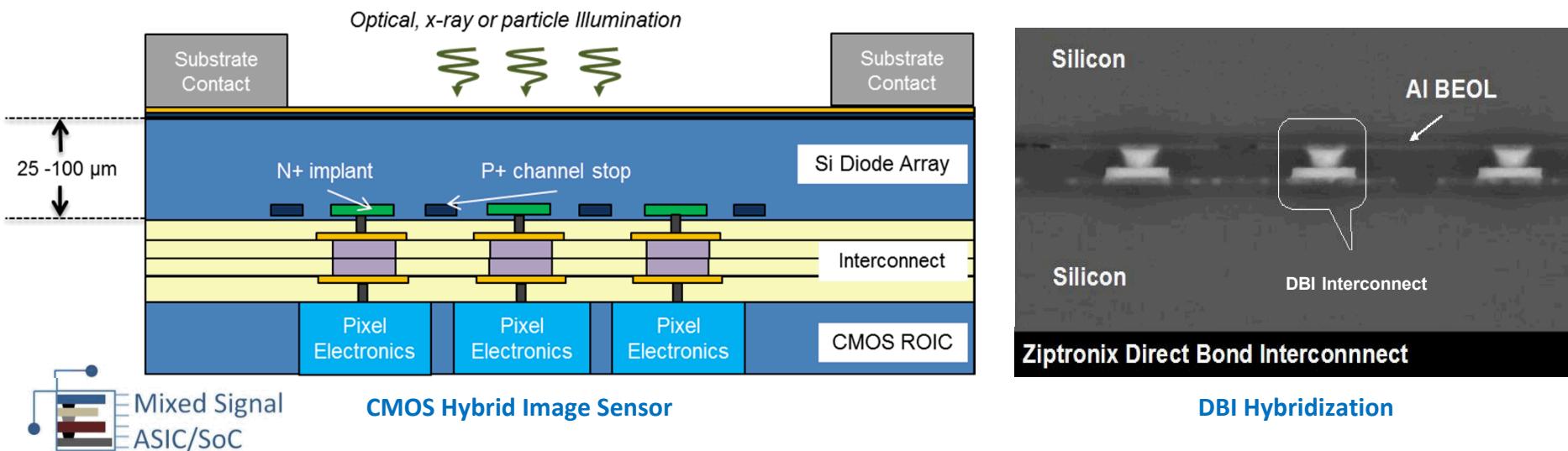
- Large detector area
- Multiple frames
- 1 ns integration time possible
- Multiple detector options for various energy spectra of interest



A hCMOS image sensor can, with X-ray source development, eliminate the need for multiple shots by capturing multiple images at user defined times within one shot

Photodiode and Hybridization

- Photodiodes can be optimized for sensitivity to relevant spectrum of interest (visible light, x-rays, electrons)
- Existing Si photodetector arrays are fabricated at SNL
- ROIC stores charge from each photodiode on in-pixel capacitors during selected integration time for each frame
- Each pixel of the photodiode array is directly connected to CMOS ROIC through wafer-to-wafer bonding (Ziptronix 3D oxide-to-oxide bond process)
- A hybrid sensor enables independent optimization of the diode array & the readout electronics (ROIC)

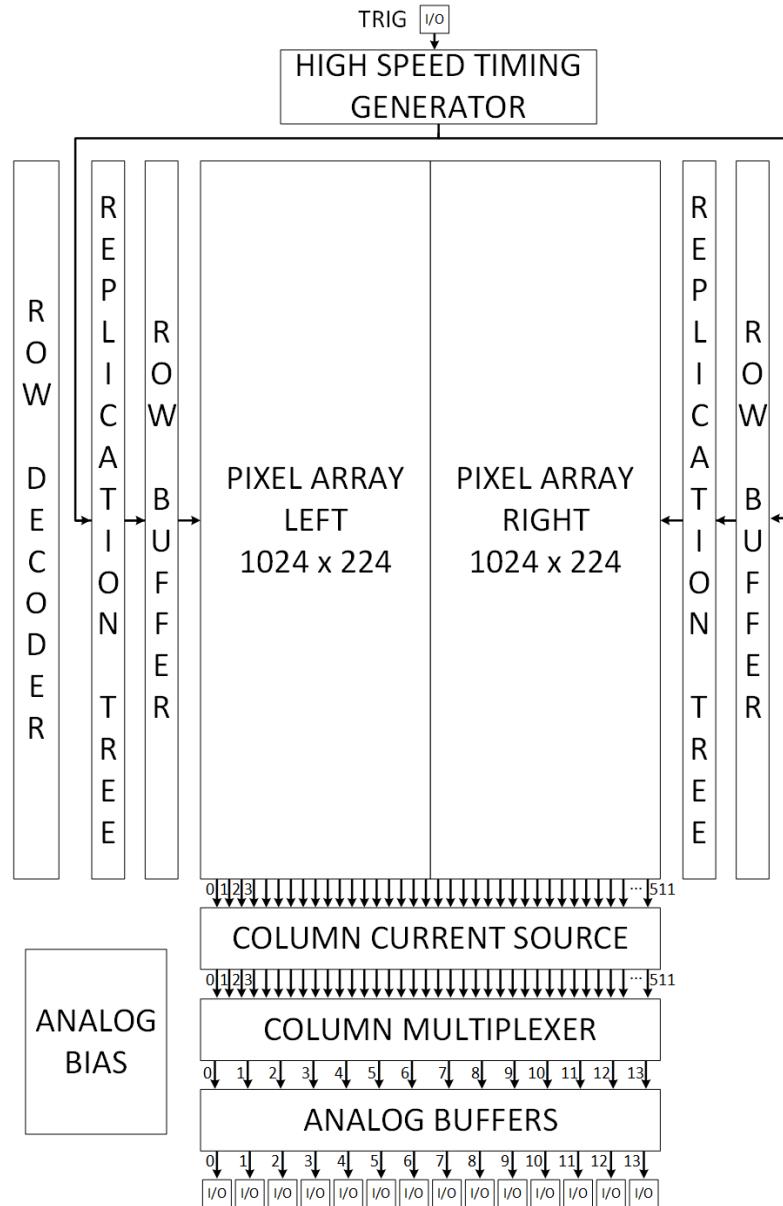


UXI Programmatic Goals

- High spatial resolution (25 μm or better)
- High speed shutters (1 ns or better)
- Many frames (8 or more frames)
- High sensitivity to visible light and single keV X-rays ($\sim 100\%$ fill-factor)
- Large dynamic range (1000:1 or better)
- Large format sensor (multi-cm scale)
- High timing precision (50 ps or better)
- Low trigger insertion delay (few 10's ns)
- Compact, rugged, and easy to integrate into diagnostic systems and experiments
- Radiation tolerant to operate in High Energy Density Physics facilities

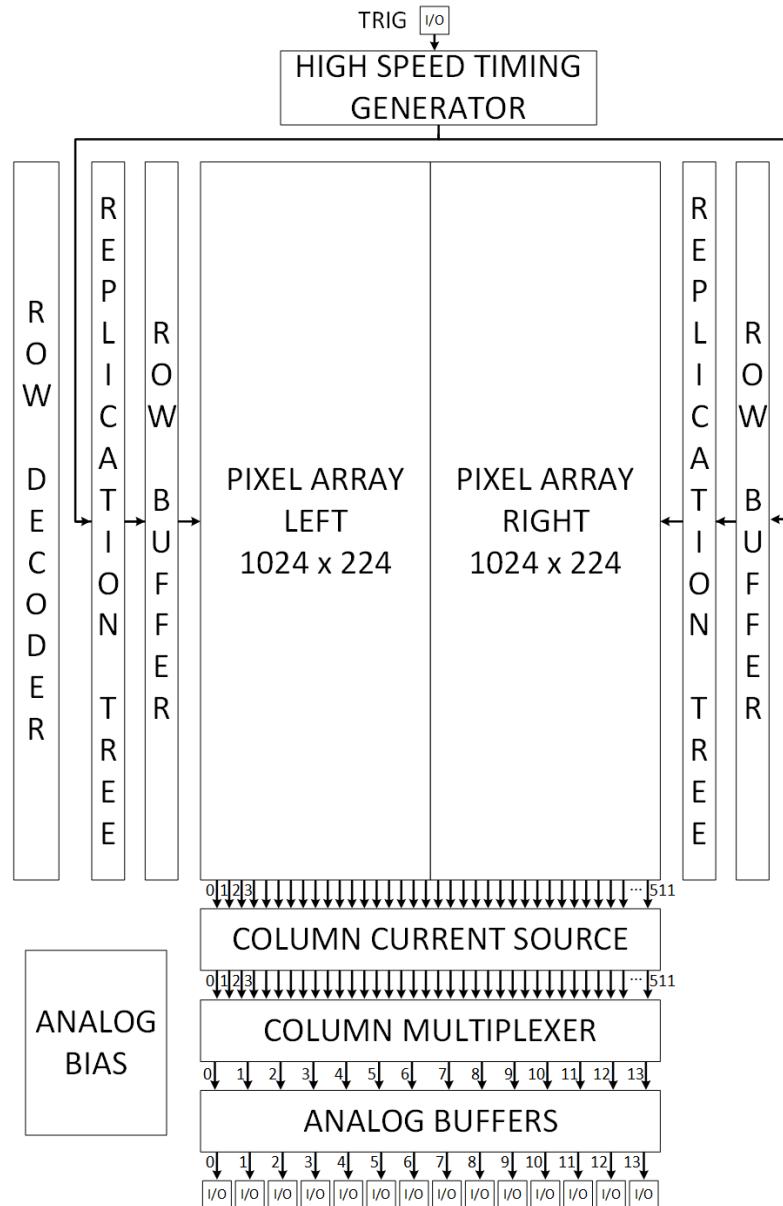
Furi Design Goals

- SNL 0.35 μm rad hard SOI technology node
- 2 frame, 25 μm pixel array
- Integration time goal < 2 ns
- Inter-frame target < 2ns
- 1024 x 448 pixel array
- 25.6 mm x 11.2 mm detector area
- 60 dB (1000:1) Dynamic Range
- Single photon (6 keV) sensitive (1600 e-)
- 1.6 million e- full well
- External, asynchronous trigger initiated
- User configurable shutter and inter-frame times



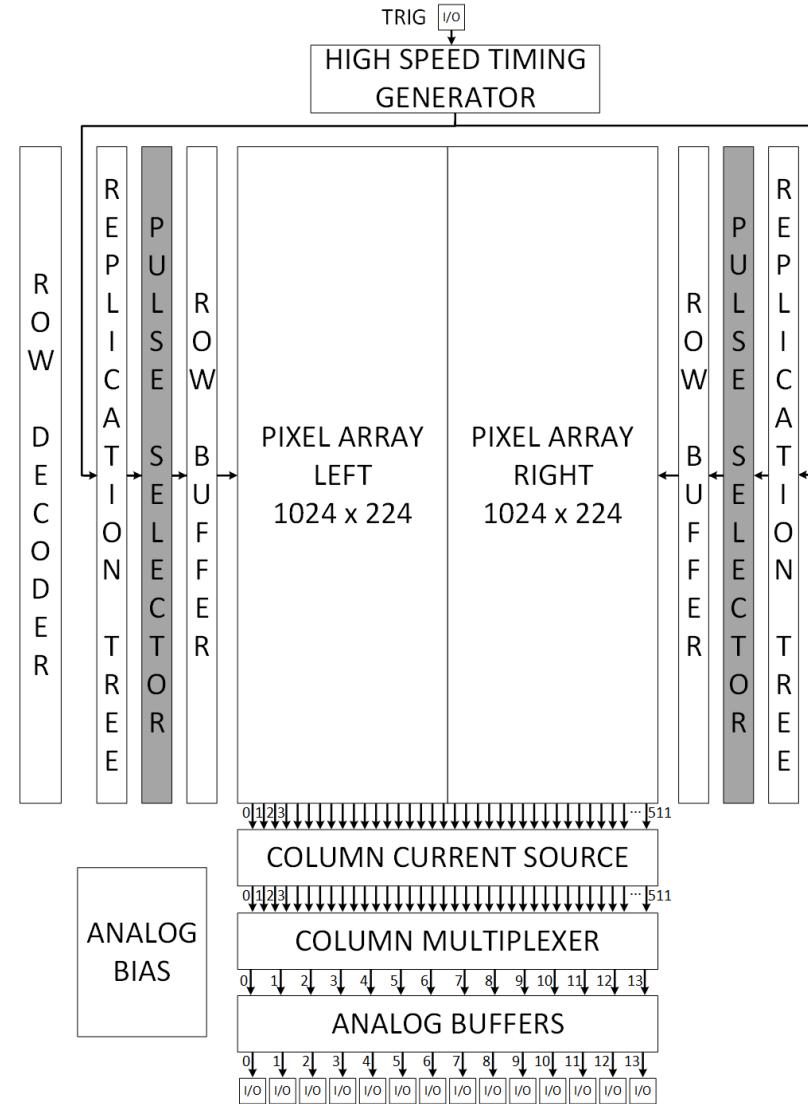
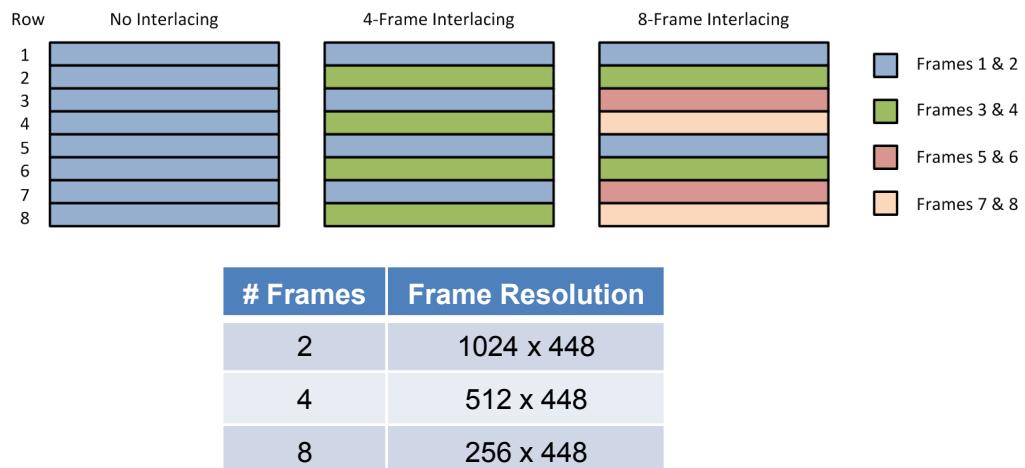
Furi Architecture

- External asynchronous trigger initiates high speed timing generator to produce the user configured shutter and inter-frame time pulses
- High speed shutter pulses are propagated from HSTGen to the pixel array through identical timing paths via a binary replication tree on both left and right hemispheres
- 2 frames of image data are stored in-situ on the pixel array and read off post experiment to external ADCs

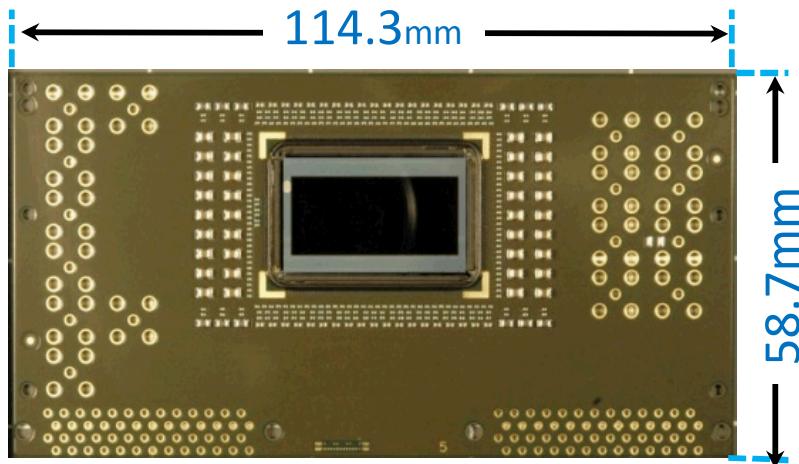


Hippogriff Architecture

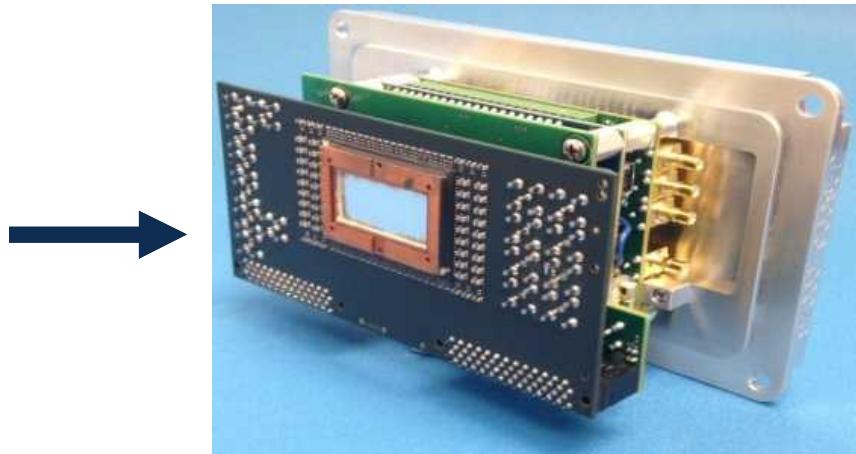
- Virtually identical to Furi with the exception of a Pulse Selector block inserted between replication tree and pixel row buffer
 - This enables row-wise interlacing so the user can trade spatial resolution for additional frames of temporal data



Packaging and System

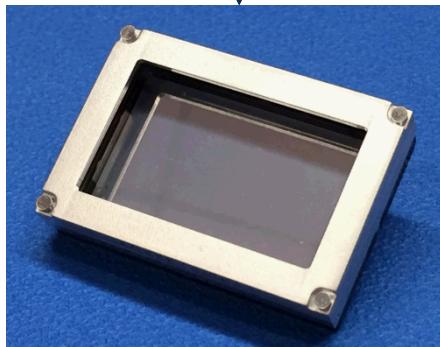


FURI Prototype Package

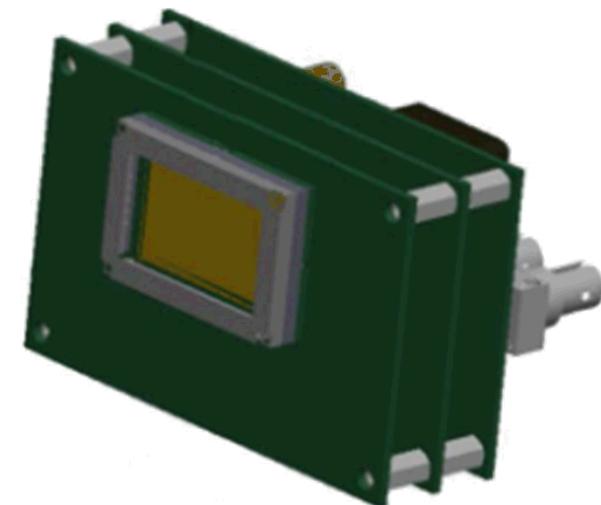


FURI Prototype Camera System

2nd Gen



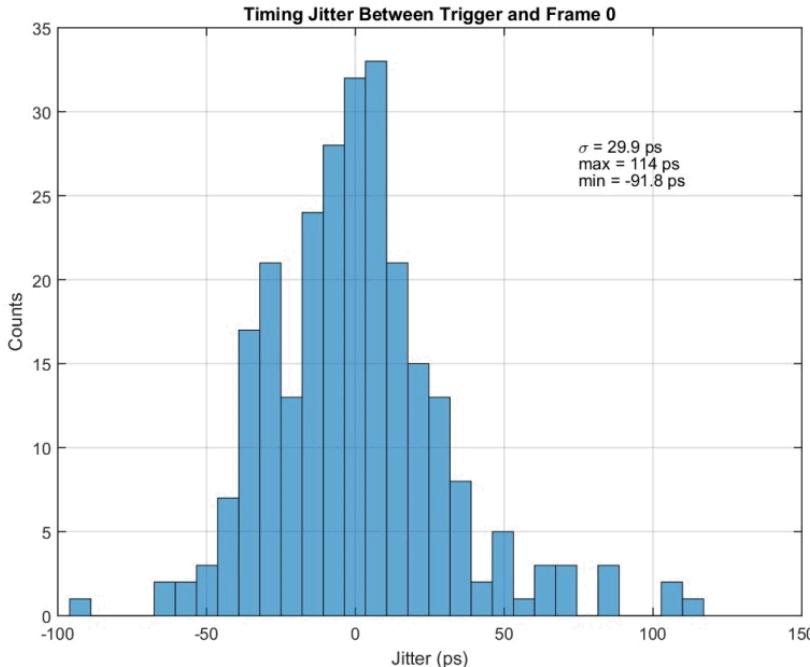
SOP Package



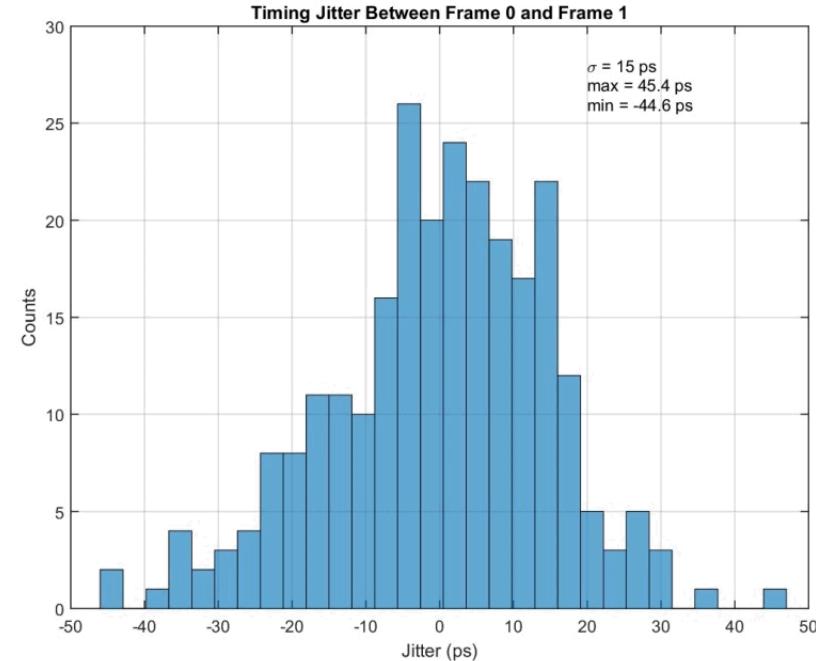
SOP Camera System-In Fabrication

Electrical Test Results-Timing

- Timing jitter tests



Measured jitter from external trigger to first frame shutter output from high speed timing generator = 30 ps rms



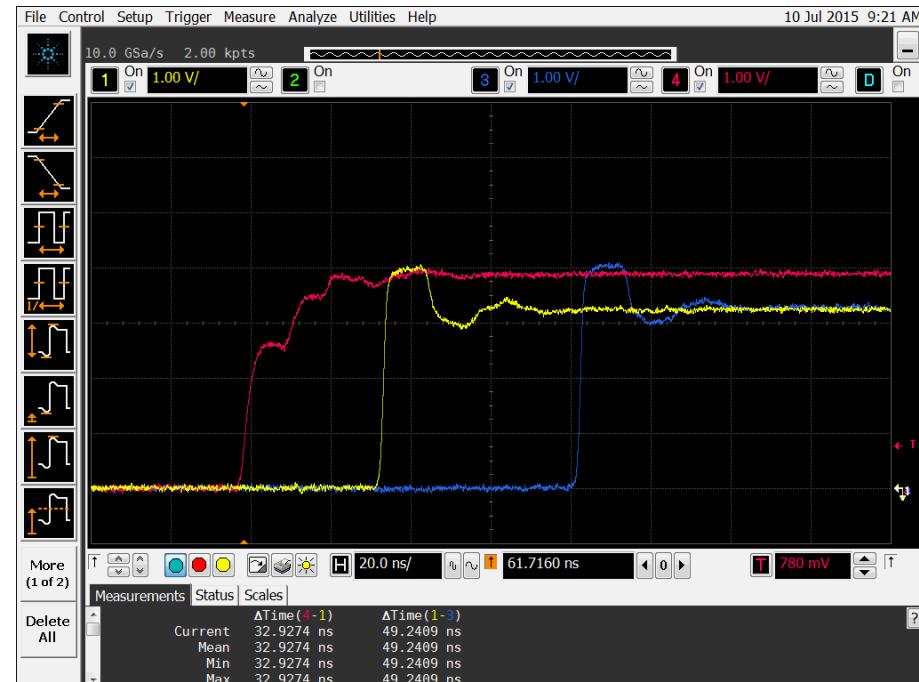
Measured jitter between shutters = 15 ps rms

Electrical Test Results-Timing

■ Insertion delay tests



Insertion delay from external trigger (red) to output of shutter pulses (Frame 0 = yellow, Frame 1 = blue) Timing configured for 10 ns on, 10 ns inter-frame time. Delay from high speed timing generator to first shutter pulse = 34 ns

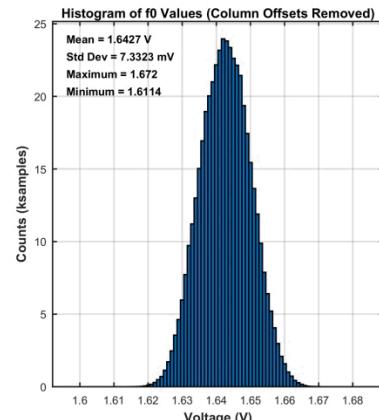


Delay from external trigger (red) to frame 0 output from high speed timing generator (yellow) and frame 0 output from row buffer (blue). Total propagation delay = 83ns

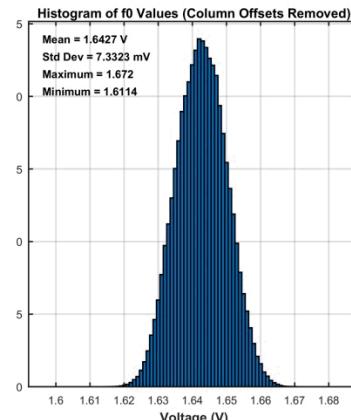
Electrical Test Results-Readout

- Fixed Pattern Noise removal with electrical flat field

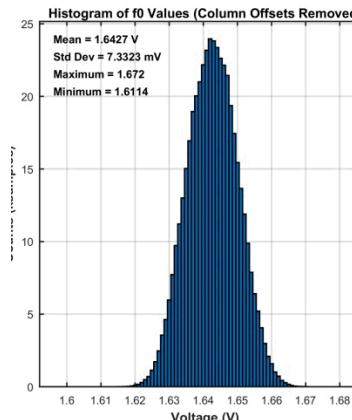
Frame 0



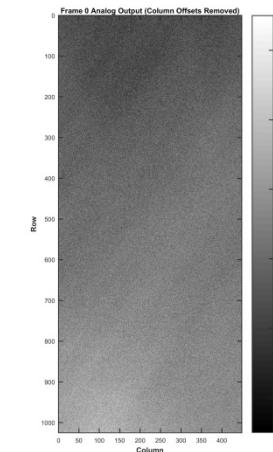
All FPN



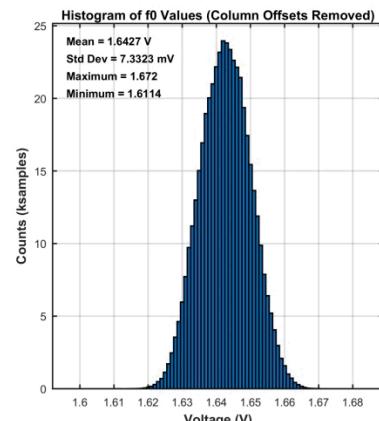
Analog Buffers Removed



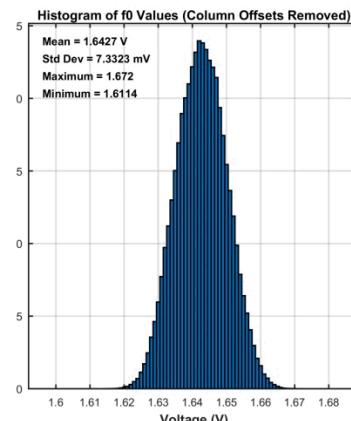
Columns Removed



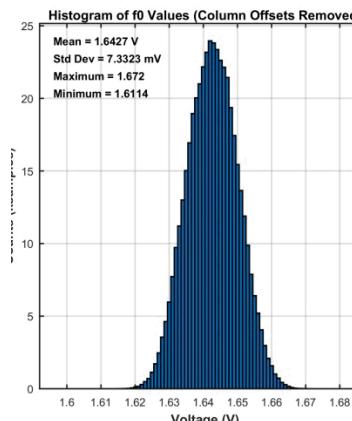
Frame 1



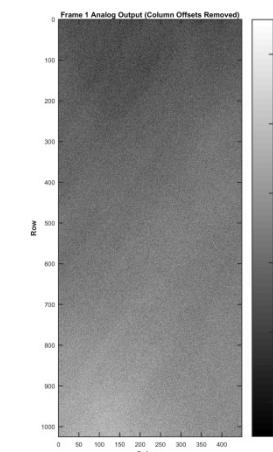
All FPN



Analog Buffers Removed

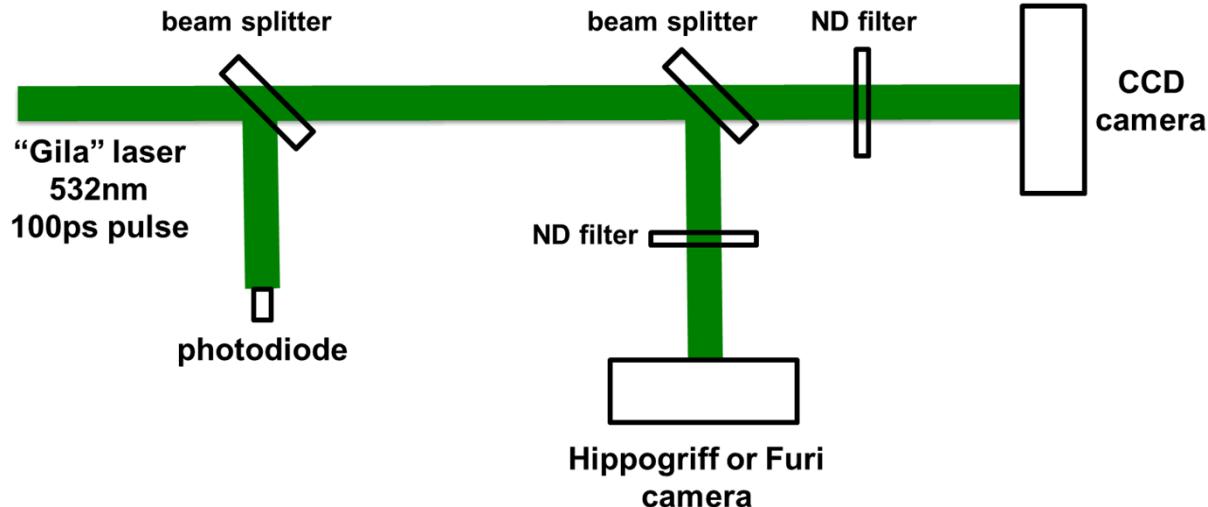


Columns Removed

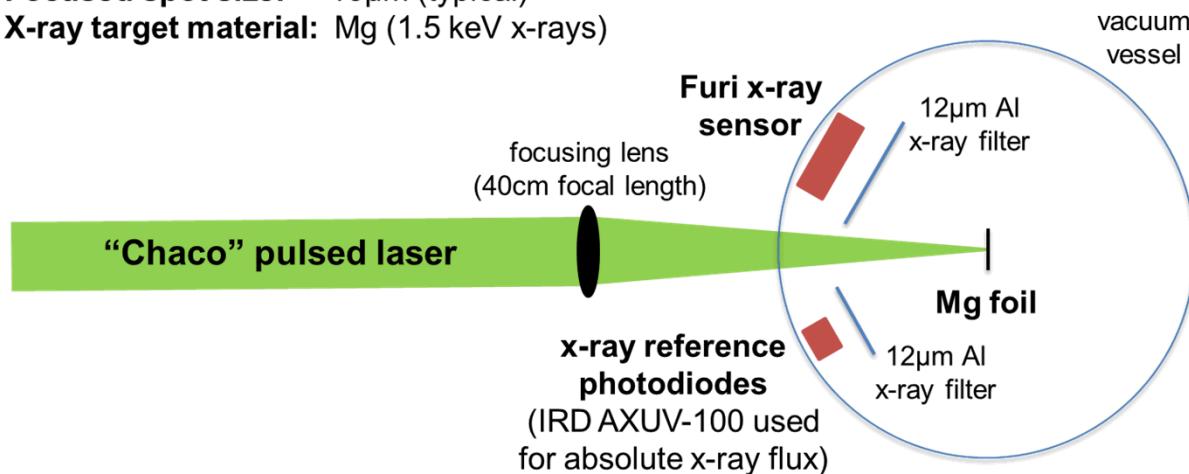


Optical Test Setup

Visible test configuration:
Produces 532 nm monochromatic light

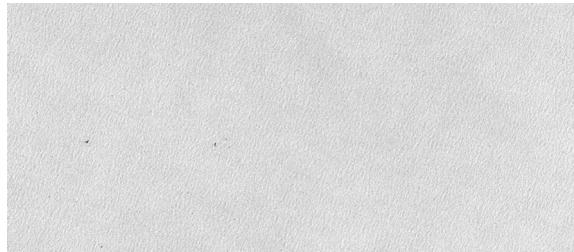


X-ray test configuration:
Produces 1.5 keV X-rays

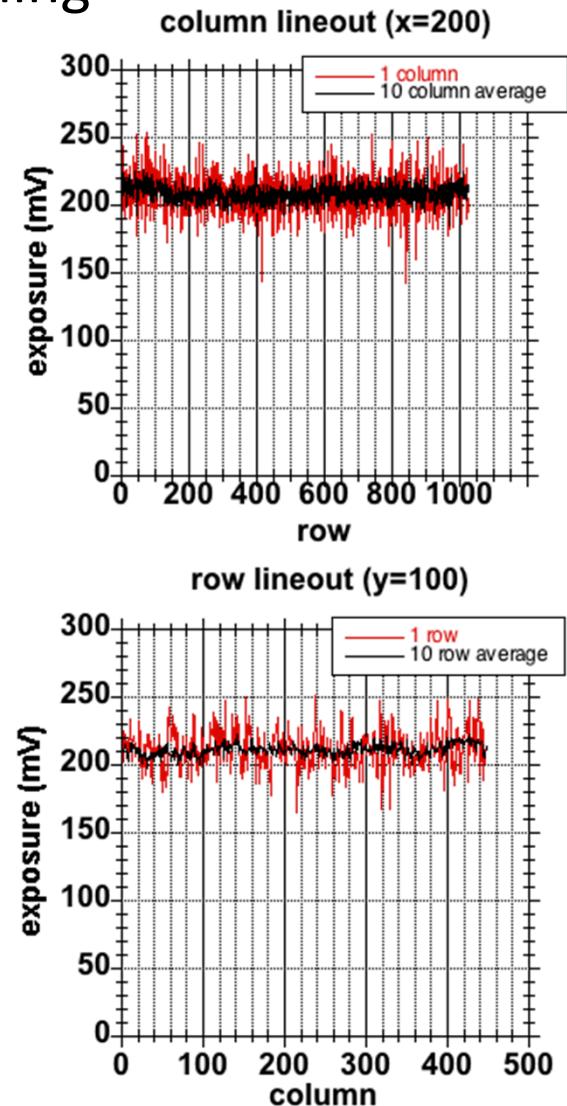
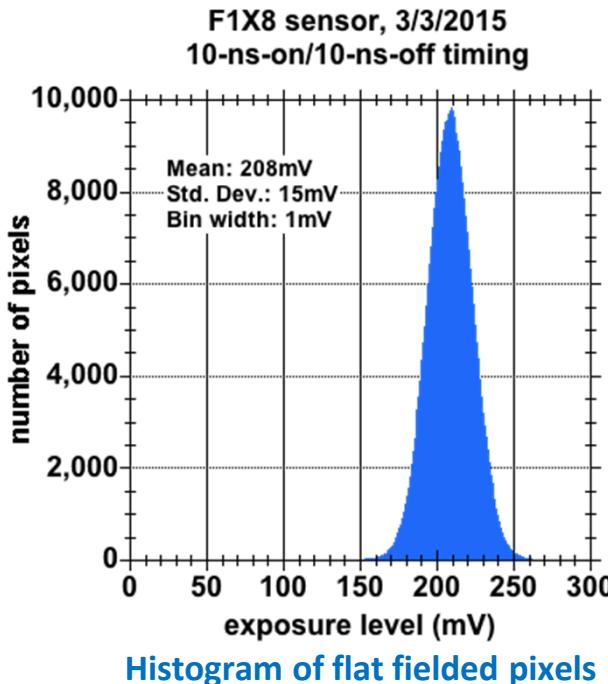


Furi X-ray flat field measurements

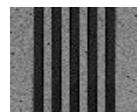
- 1.5 keV X-ray fluence, 10ns shutter timing



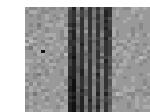
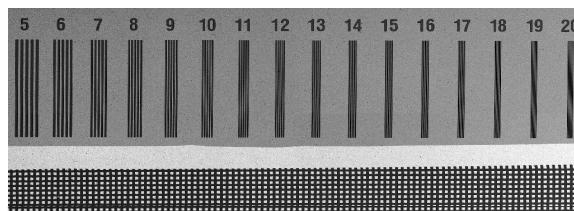
208 mV average exposure, ~500 photons/pixel



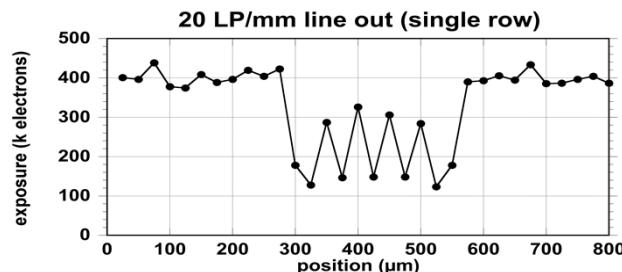
X-ray spatial resolution/DR measurements



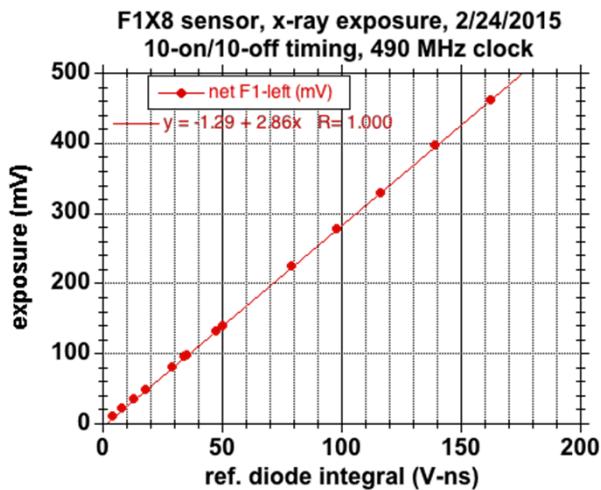
5 LP/mm
64 x 64
pixels



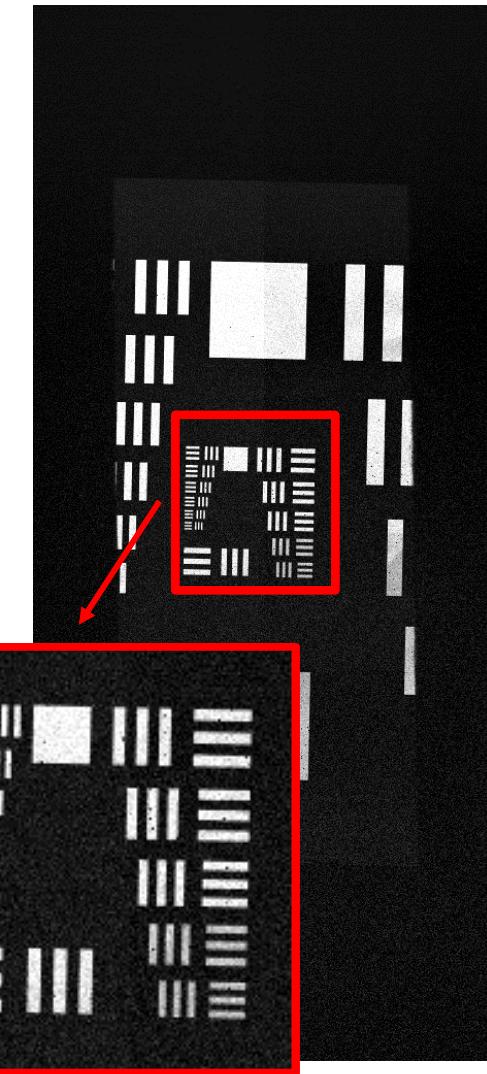
20 LP/mm
32 x 32
pixels



Line Pair X-Ray Test Pattern: 2 ns integration time



Dynamic Range Sweep: 10 ns integration time

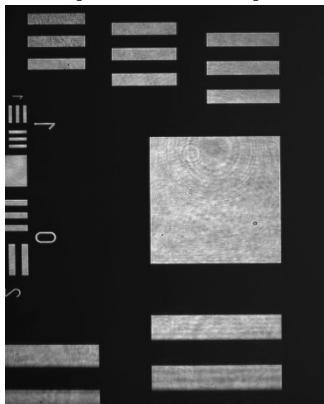


Air Force Test Pattern: 2 ns integration time

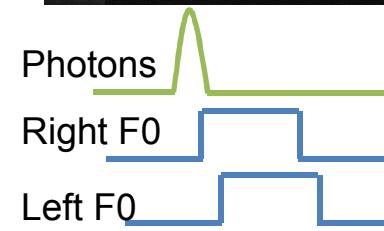
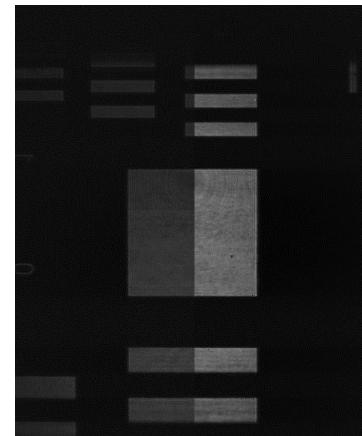
Spatial analysis for 1 ns-on/1 ns-off timing, visible illumination

- Swept the optical pulse through the shutter window in 100 ps time steps
- Observed a fixed hemispheric skew from left to right

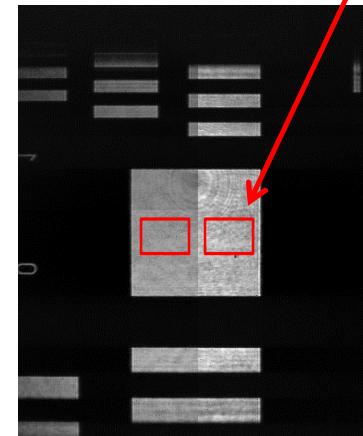
CCD reference
image
(shot 63)



Furi F0 image
(shot 58)

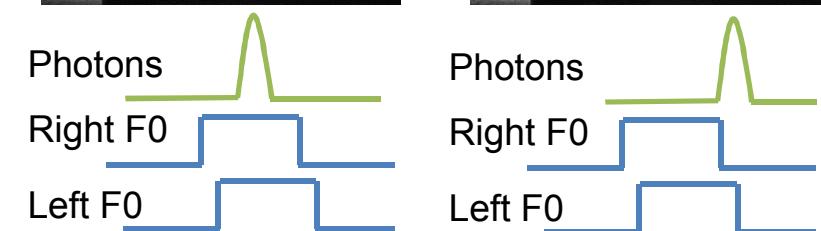
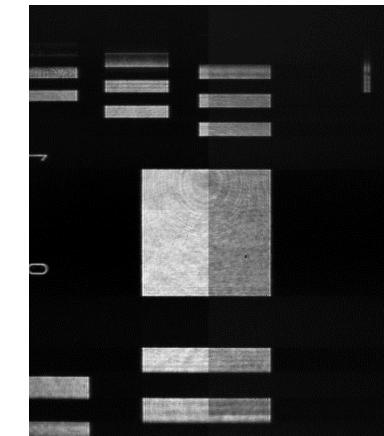


Furi F0 image
(shot 63)

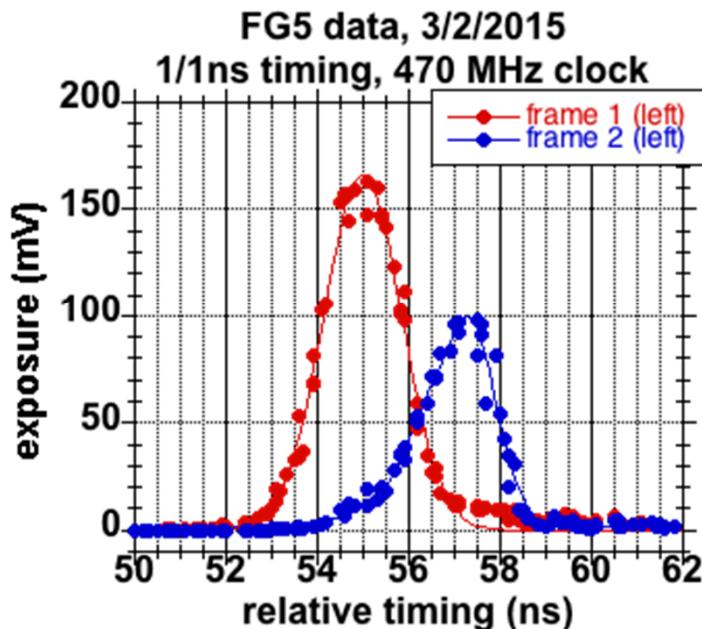


ROIs used in analysis

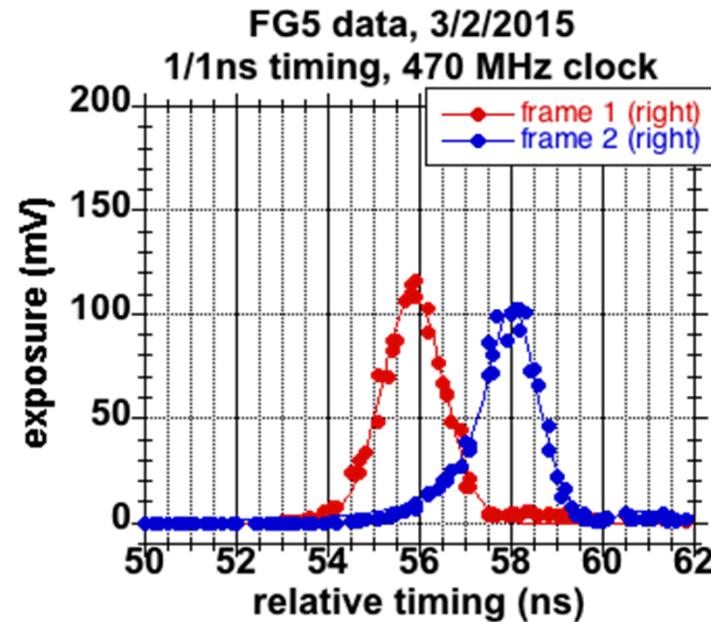
Furi F0 image
(shot 68)



Temporal analysis for 1 ns-on/1 ns-off timing, visible illumination

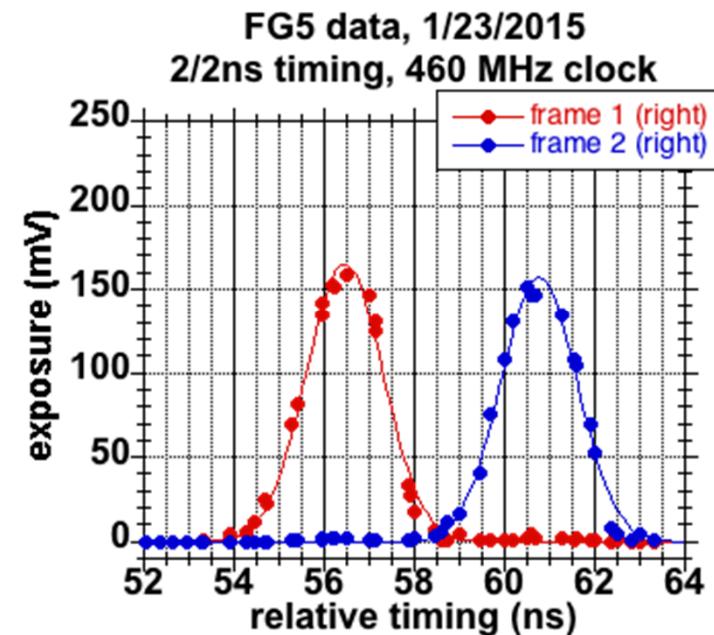
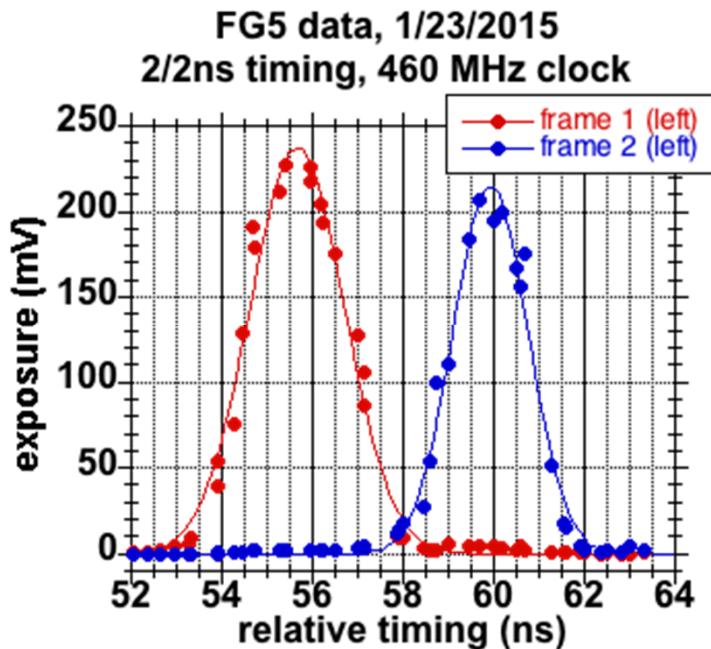


	FWHM (ns)	Frame Δt (ns)	left/right Δt (ns)
frame 1	2.0		0.9
frame 2	1.9	2.3	0.8



	FWHM (ns)	Frame Δt (ns)	left/right Δt (ns)
frame 1	1.6		0.9
frame 2	1.6	2.1	0.8

Temporal analysis for 2 ns-on/2 ns-off timing, visible illumination

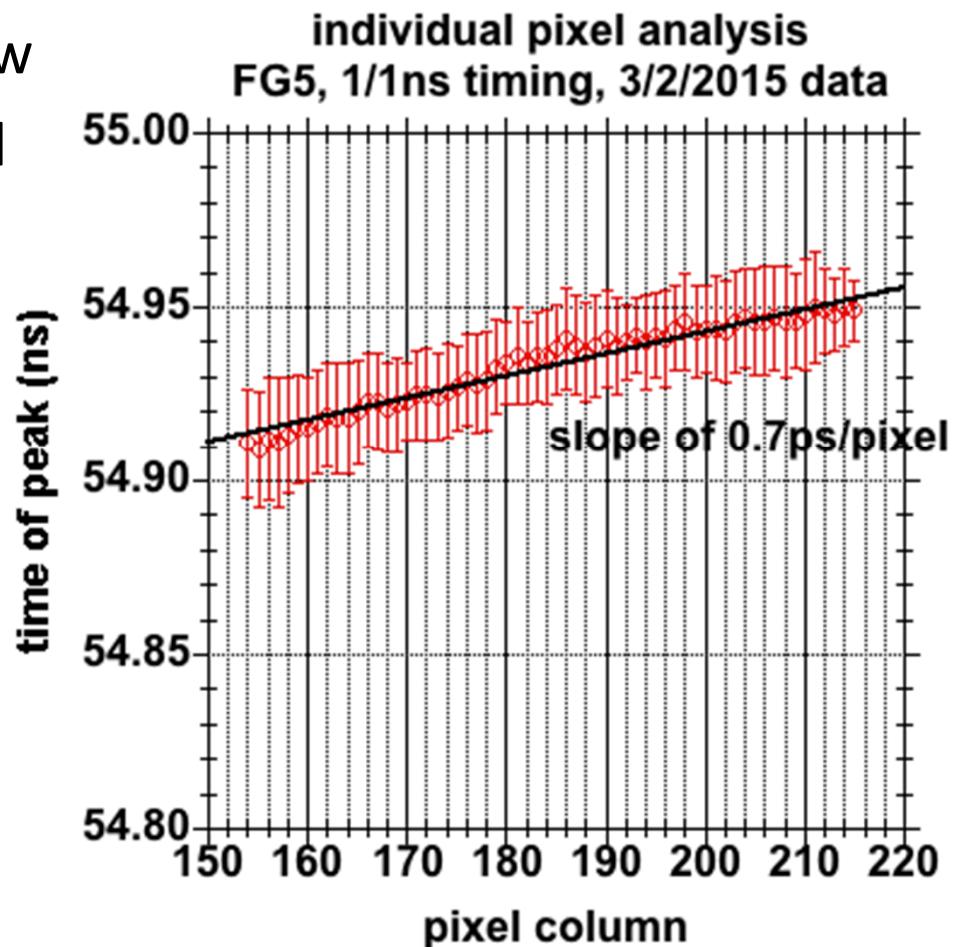


	FWHM (ns)	Frame Δt (ns)	left/right Δt (ns)
frame 1	2.4		0.8
frame 2	1.9	4.2	0.9

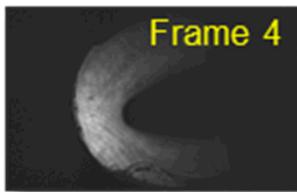
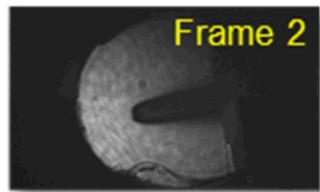
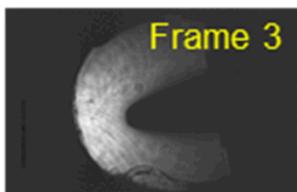
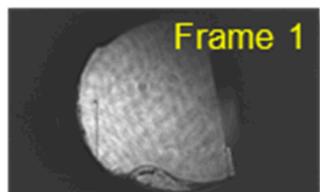
	FWHM (ns)	Frame Δt (ns)	left/right Δt (ns)
frame 1	2.0		0.9
frame 2	2.0	4.3	0.8

Timing distribution “skew” for 1ns-on/1ns-off timing, visible illumination

- Expected timing skew across the array due to RC of pixel row
- Simulated to be ~1ps/pixel

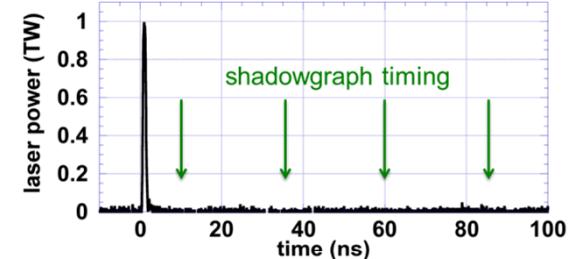
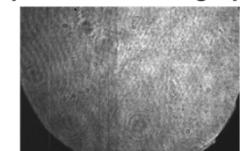


Dynamic Optical Results (X-ray and Visible)



Hippogriff, 4 ns timing, x nm (keV) illumination

preshot shadowgraph

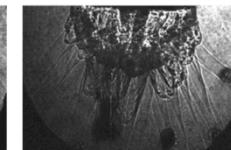
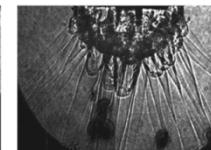
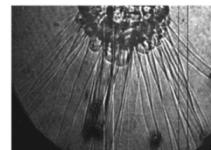
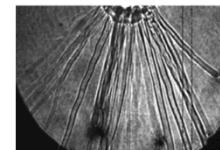


5.6mm

9.2mm

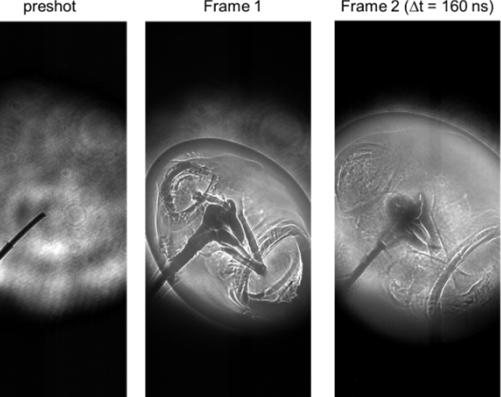
11.1mm

12.4mm

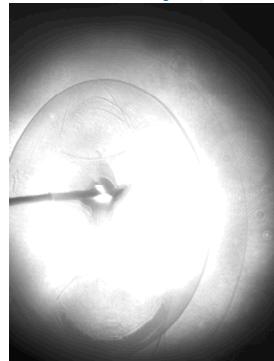


2 Furi cameras, x ns timing, 532 nm illumination

Furi Sensor



Commercial CCD,
double exposed



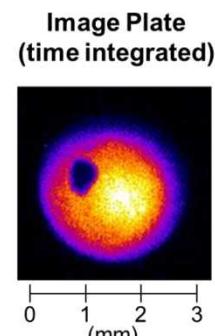
Furi, 10 ns integration, 150 ns inter-frame, 532 nm illumination

IP exp.
(PSL)

0.50

0.25

0



Furi
(frame 1)

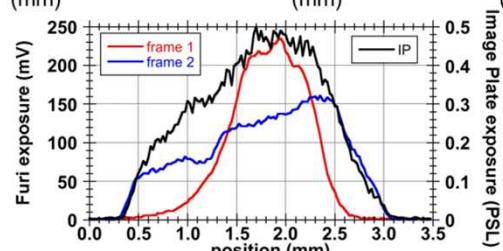
Furi
(frame 2)

Furi exp.
(mV)

300

150

0



Furi, 9ns integration, 1ns inter-frame, X-ray illumination

Conclusion and Team

- Team Members also?

Spec	Goal	Furi
Spatial Resolution	25 um	25 um
High Speed Shutters	< 1ns	1.5-2 ns
Many Frames	> 8	2 (8 with Hippogriff)
Sensitivity	Visible and 6 keV X-ray	Yes
Dynamic Range	60 dB	Yes
Large Sensor Area	cm scale	2.56 cm x 1.12 cm
Timing Precision	50 ps	900 ps
Trigger Delay	10's of ns	83 ns
Camera Physical Size	Small	Reasonable (2 nd gen SOP)
Radiation Tolerance	Survive Z-shot	In progress but confident

ROIC Timeline

	Griffin	Furi	Hippogriff	Icarus	Acca
Year	FY13	FY14	FY15	FY16	FY17
Min. Gate Time			1.5ns		
Pixels			448 x 1024		
Frames		2	2, 4, or 8 (interlaced)		
Sensor Types		500-900nm, 0.7-6keV			
Tiling Option			No		
CMOS Process			350nm		
Status	Completed		Packaging & Characterization		

